## **Supporting Information**

## 3D Topological Dirac Semimetal/MoO<sub>3</sub> Thin Film Heterojunction Infrared Photodetector with Current Reversal Phenomenon

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**Fig. S1** Schematic diagram of the fabrication process of DSMs thin film/MoO<sub>3</sub> composite thin film and array device.



**Fig. S2** XPS pattern of 100 nm  $Cd_{1-x}Znx)_3As_2$  thin film. (a) The XPS survey curve of  $Cd_{1-x}Znx)_3As_2$  thin film. (b),(c),(d) The XPS peak curve of Cd, Zn, As element.



**Fig. S3** EDS mapping of  $(Cd_{1-x}Znx)_3As_2$  thin films. (a) Image of test area. (b), (c), (d) The EDS mapping images of Cd, Zn and As element, respectively.

**Table S1** The charge transport properties (mobility, carrier type and conductivity) of prepared  $(Cd_{1-x}Zn_x)_3As_2$  thin film.

Sample	(Cd <sub>1-x</sub> Znx) <sub>3</sub> As <sub>2</sub> thin film (100 nm)		
Carrier type	Ν	Hall coefficient (cm <sup>3</sup> /C)	-26.8
Carrier surface density (cm <sup>-2</sup> )	2.3E12	Resistivity (Ωcm)	1.6
Carrier body density (cm <sup>-3</sup> )	2.3E17	Conductivity (1/Ωcm)	0.6
Carrier mobility (cm <sup>2</sup> /Vs)	16.3	f factor	0.99

Note:Test method: Vanderbilt method

The calculation formula is as follows:

n=B/(eR<sub>xy</sub>t), where e is the element charge and t is the thickness of the sample.  $\mu$ =2206\*R<sub>xy</sub>/B/R<sub>xx</sub> (unit: cm<sup>2</sup> / Vs)



Fig. S4 (a) The  $I_{ph}$  curves of device as a function under different  $V_{bias}$ . (b) The  $I_{ph}$  curves of device as a function under different power density, while  $V_{bias}=1$  V.



**Fig.** S5 (a), (b) The performance influence of different annealing temperatures (20 °C, 40 °C, 60 °C, 80 °C, 100 °C, 120 °C, 140 °C) on  $(Cd_{1-x}Zn_x)_3As_2/MoO_3$  thin film heterojunction device.



**Fig. S6** (a), (b), (c), (d) The surface topography of  $(Cd_{1-x}Zn_x)_3As_2$  thin film at different temperatures (20 °C, 80 °C, 100 °C, 140 °C). The test area was 20  $\mu$ m×20  $\mu$ m. The RMS roughness of  $(Cd_{1-x}Zn_x)_3As_2$  thin film under different post-growth anneal temperatures is 22.2 nm, 19.3 nm, 17.0 nm, 18.8 nm, respectively.



Fig. S7 Current variation characterization of  $(Cd_{1-x}Zn_x)_3As_2/MoO_3$  (50 nm/100 nm) device. (a), (b) The heating and cooling process of  $(Cd_{1-x}Zn_x)_3As_2/MoO_3$  (50 nm/100 nm) device, respectively.



Fig. S8 (a) The  $R_i$  curves of different thickness  $(Cd_{1-x}Zn_x)_3As_2$  thin film photodetectors at different wavebands. (b) The  $R_i$  curves of 100 nm  $(Cd_{1-x}Zn_x)_3As_2$  with different thickness of MoO<sub>3</sub> at different wavebands.



**Fig. S9** The response time of  $(Cd_{1-x}Zn_x)_3As_2/MoO_3$  heterojunction thin film photodetector @ 808 nm. The rise time ( $\tau_{on}$ ) and decay time ( $\tau_{off}$ ) are obtained by defining the time for the photocurrent rising from 10 % to 90 % and declining from 90 % to 10 %, respectively



**Fig. S10** The noise diagram of pure DSMs thin film device and DSMs/MoO<sub>3</sub> thin film heterojunction device.



Fig. S11 The relationship between the  $R_i$  and  $D^*$  of the DSMs/MoO<sub>3</sub> thin film heterojunction device and the laser power density changes. With the decrease of the laser power, the  $R_i$  and  $D^*$  increase linearly.



Fig. S12 The absorption curves of  $(Cd_{1-x}Zn_x)_3As_2/MoO_3$  combined thin films from VL to MLIR region. (a) The region from 200 nm to 1400 nm. (b) The region from 1.5  $\mu$ m to 4.6  $\mu$ m.